

<b>To:</b> SiliconSystems Customers	<b>DATE:</b> April 30, 2005
<b>FROM:</b> David E. Merry, CTO	<b>RE:</b> RoHS Compliance Roadmap

## OVERVIEW

The European Union (E.U.) has passed into law the Restriction of Hazardous Substances in Electrical and Electronic Equipment (RoHS) Directive, which will ban the use of four metals and two flame retardants in electronic products sold in Europe beginning July 1, 2006. Other governments including China and Japan are enacting similar legislation and in the United States, California is also in the process of adopting similar requirements.

SiliconSystems, Inc. has developed a road map to ensure that we comply with applicable legal and regulatory standards for the protection of the environment. This includes but is not limited to:

- Development of products that are safe and make efficient use of resources that can be reused, recycled and disposed of safely
- Appointment of competent people to assist us in meeting RoHS compliance
- Investigation of our supply chain to ensure manufacturing processes and systems are in line with SiliconSystems' RoHS Compliance Schedule
- Working with our customers to ensure minimum disruption in the implementation of the RoHS Directive.

Environmental concerns about lead are forcing its removal from electronics and computing products. As the legislation and associated standards continue to develop, some aspects and timetables may change and the information contained within these pages may be altered to reflect these factors.

The RoHS Directive bans the use of six hazardous materials. As defined, the limits apply to individual "homogeneous" materials within a product.

- Metals: Lead < 0.1%, Cadmium < 0.01%, Hexavalent Chromium < 0.1%, Mercury < 0.1%.
- Brominated flame-retardants: Polybrominated biphenyls (PBB) 0.1% max, Polybrominated diphenyl ethers (PBDE) 0.1% max.

Typical items that may contain one or some of the above are as follows:

- Lead: Printed circuit board finishes, component lead tinning, wire tinning, solder.
- PBDE/PBB: Connectors Wire and other component sleeve, plastic film capacitors

## SILICONSYSTEMS COMPLIANCE SCHEDULE

Phase 1 – Scheduled Completion July 2005

- Product Disposition, Components and Business Systems
- Component Identification, Substitutions and Qualification
- Supplier Compliance
- IT System Upgraded to Ensure Compliance

Phase 2 – Scheduled Completion October 2005

- SiliconDrive Product Transition - SiliconDrives designs currently in production will continue to be available, as will their RoHS-compliant equivalents
- Board Finishes
- Documentation
- Marking and Identification
- RoHS-compliant Samples Available

Phase 3 – Scheduled Completion December 2005

- Process Transition
- Solder Paste
- Wave Solder bath
- Full Production

Note: Custom SiliconDrives may have varying dispositions of compliance specific to customer requirements and/or applications.

All new products commencing the design cycle with effect from April 30, 2005 will exclusively employ RoHS-compliant components.

Best Regards,



David E. Merry  
Chief Technology Officer  
SiliconSystems, Inc.